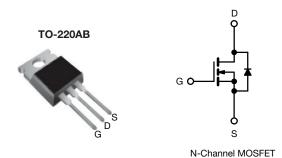
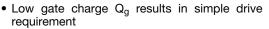


Power MOSFET



PRODUCT SUMMA	RY	
V _{DS} (V)	500)
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	0.52
Q _g max. (nC)	52	
Q _{gs} (nC)	13	
Q _{gd} (nC)	18	
Configuration	Sing	le

FEATURES





Improved gate, avalanche, and dynamic dV/dt ruggedness

RoHS³

- Fully characterized capacitance and avalanche voltage and current
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- High speed power switching

APPLICABLE OFF LINE SMPS TOPOLOGIES

- Two transistor forward
- Half and full bridge
- Power factor correction boost

ORDERING INFORMATION	
Package	TO-220
Lead (Pb)-free	IRFB11N50APbF
Lead (Pb)-free and halogen-free	IRFB11N50APbF-BE3

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	500		
Gate-source voltage		V _{GS}	± 30	V		
Continuous drain surrent	\/ at 10 \/	T _C = 25 °C	,	11		
Continuous drain current	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I _D	7.0	А	
Pulsed drain current ^a			I _{DM}	44	1	
Linear derating factor				1.3	W/°C	
Single pulse avalanche energy ^b	rgy ^b E _{AS} 275 mJ		mJ			
Repetitive avalanche current a			I _{AR}	11	А	
Repetitive avalanche energy ^a			E _{AR}	17	mJ	
Maximum power dissipation	$T_C = 3$	25 °C	P _D	170	W	
Peak diode recovery dV/dt ^c			dV/dt	6.9	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	00	
Soldering recommendations (peak temperature) ^d	For 10 s			300	°C	
Maunting towns	6-32 or M3 screw			10	lbf ⋅ in	
Mounting torque	0-32 Or N	no screw	1.1 N·m			

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Starting T_J = 25 °C, L = 4.5 mH, R_G = 25 Ω , I_{AS} = 11 A (see fig. 12)
- c. $I_{SD} \le 11$ A, $dI/dt \le 140$ A/µs, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C
- d. 1.6 mm from case



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THERMAL RESISTANCE				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	0.75	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500	-		V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} :	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	-	± 100	nA
Zone mate veltage due in account		V _{DS} =	V _{DS} = 500 V, V _{GS} = 0 V		-	25	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 400 \	/, V _{GS} = 0 V, T _J = 150 °C	-	-	250	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 6.6 A ^b	-	-	0.52	Ω
Forward transconductance	9 _{fs}	V_{DS}	= 50 V, I _D = 6.6 A	6.1	-	-	S
Dynamic							
Input capacitance	C _{iss}		$V_{GS} = 0 V$	-	1423		
Output capacitance	C _{oss}	1	$V_{DS} = 25 \text{ V},$	-	208	-	
Reverse transfer capacitance	C _{rss}	f = 1	.0 MHz, see fig. 5	-	8.1	-	
Output conscitones	0		V _{DS} = 1.0 V, f = 1.0 MHz	-	2000	-	pF
Output capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 400 V, f = 1.0 MHz	-	55	-	1
Effective output capacitance	C _{oss} eff.	1	V _{DS} = 0 V to 400 V	-	97	-	
Total gate charge	Q_g		I _D = 11 A, V _{DS} = 400 V see fig. 6 and 13 ^b	-	-	52	nC
Gate-source charge	Q_{gs}	V _{GS} = 10 V		-	-	13	
Gate-drain charge	Q_{gd}	1	occ lig. o and ro	=	-	18	
Turn-on delay time	t _{d(on)}	V_{DD} = 250 V, I_{D} = 11 A R_{G} = 9.1 Ω , R_{D} = 22 Ω , see fig. 10 b		-	14	-	ns
Rise time	t _r			-	35	-	
Turn-off delay time	t _{d(off)}			-	32	-	
Fall time	t _f			-	28	-	
Gate input resistance	R_g	f = 1 MHz, open drain		0.5	-	3.2	Ω
Drain-Source Body Diode Characteristi	cs						
Continuous source-drain diode current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	11	- A
Pulsed diode forward current ^a	I _{SM}	integral reverse p - n junction diode		-	-	44	
Body diode voltage	V_{SD}	T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V b		-	-	1.5	V
Body diode reverse recovery time	t _{rr}	T 05 00 1			510	770	ns
Body diode reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = 11 \text{A}, dI/dt = 100 \text{A/} \mu \text{s}^{ \text{b}}$		-	3.4	5.1	μC
Forward turn-on time	t _{on}	Intrinsic tu	on is dor	ninated b	y L _S and	L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11) b. Pulse width \leq 300 $\mu s;$ duty cycle \leq 2 %
- c. C_{oss} effective is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

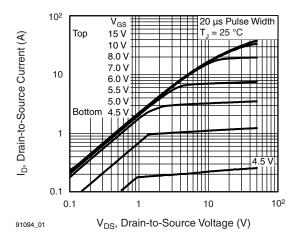


Fig. 1 - Typical Output Characteristics

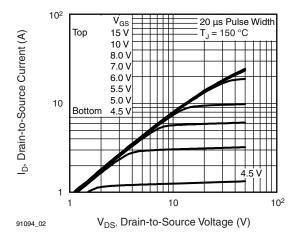


Fig. 2 - Typical Output Characteristics

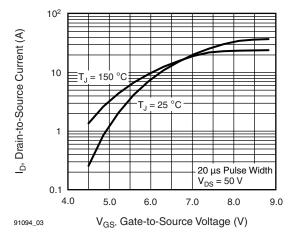


Fig. 3 - Typical Transfer Characteristics

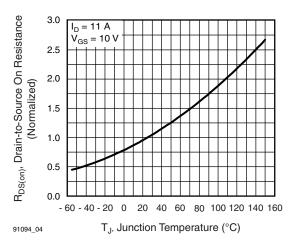


Fig. 4 - Normalized On-Resistance vs. Temperature

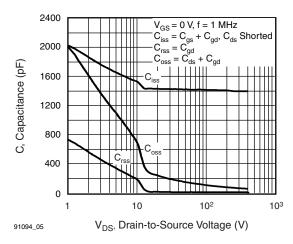


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

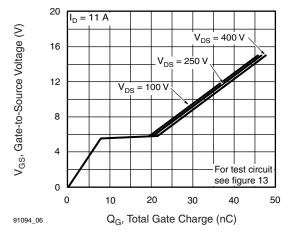


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



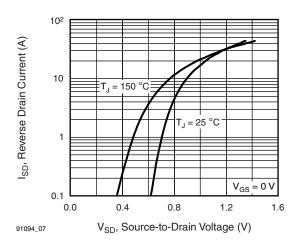


Fig. 7 - Typical Source-Drain Diode Forward Voltage

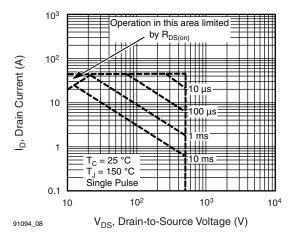


Fig. 8 - Maximum Safe Operating Area

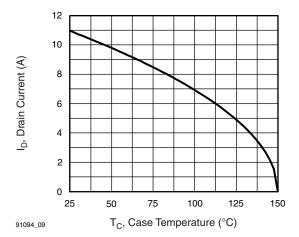


Fig. 9 - Maximum Drain Current vs. Case Temperature

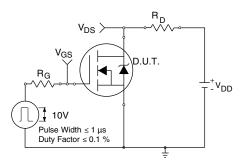


Fig. 10a - Switching Time Test Circuit

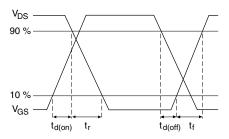


Fig. 10b - Switching Time Waveforms



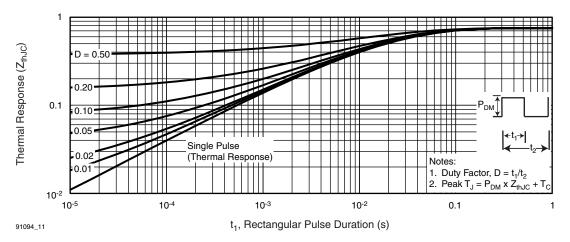


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

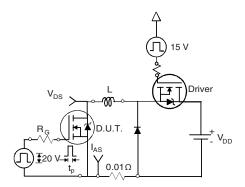


Fig. 12a - Unclamped Inductive Test Circuit

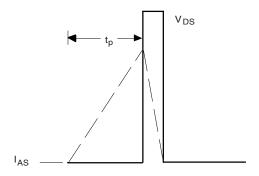


Fig. 12b - Unclamped Inductive Waveforms

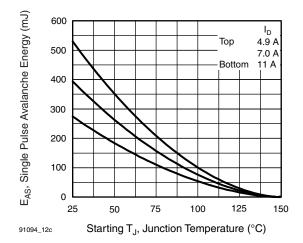


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

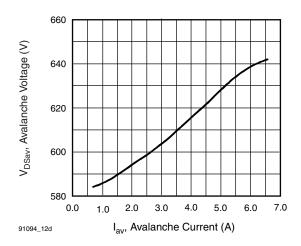


Fig. 12d - Typical Drain-to-Source Voltage vs. Avalanche Current

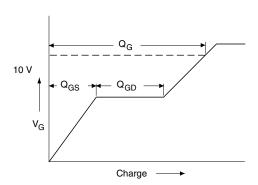


Fig. 13a - Basic Gate Charge Waveform

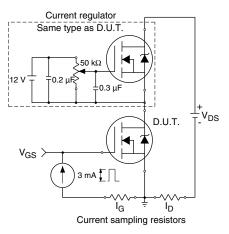
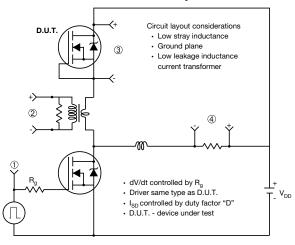


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



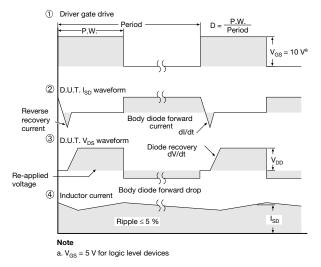


Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIM	IETERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØΡ	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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